



Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408)943-2600

PRODUCT INFORMATION NOTIFICATION

PIN: PIN145344

Date: December 08, 2014

Subject: Qualification of Die Attach Film for 48 Ball Grid Array (BGA) Stack Die Packages

To: PCN ADMIN
CYPRESS
pcn_adm@cypress.com

Change Type: Minor

Product Information:

Cypress announces the qualification of die attach film to replace die attach epoxy at Advanced Semiconductor Manufacturing - Taiwan (ASE Kaohsiung) on 48BGA stack die packages. This is to improve process control resulting in better product quality and field reliability. This is a fan-out from other 48BGA stack die conversions to die attach film released in Q1 2014 under PCN145278, which have now been in full production mode for over six months. PCN145278 can be obtained at www.cypress.com/pcn.

New and Current Bill of Materials:

Material	New Bill of Materials (ASE Kaohsiung)	Current Bill of Materials (ASE Kaohsiung)
Mold Compound	Kyocera KE-G2270	Kyocera KE-G2270
Die Attach	Henkel ATB – 125 (Film)	Ablestick 2025D & QMI 536 (Epoxy)
Bond Wire	Au, 1.0 mil	Au, 1.0 mil
Lead Finish	Sn/Ag/Cu	Sn/Ag/Cu

The new die attach film has been qualified through a series of tests documented in Qualification Test Plan (QTP) 135002. The qualification report can be found as an attachment to this notification or by visiting www.cypress.com and typing the QTP number in the keyword search window.

Affected Part Numbers: 16

Affected Parts: Please refer to the attached affected part list

Approximate Implementation Date:

Effective 14 days from the date of this notification, Cypress will start to transition to shipments of the affected part numbers with the newly qualified die attach film.

Anticipated Impact:

None anticipated. Products manufactured at ASE Kaohsiung with the new die attach film are completely compatible with existing product from a functional and parametric performance perspective; quality and reliability are enhanced with the die attach film process, eliminating a lifted-ball failure mode with the existing epoxy part.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication and assembly location, through the lot number marked on the package. There will be no changes to the ordering codes or marking on production material shipped after the change implementation date.

Response Required:

This is an information only announcement. No response is required

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration

Item	Marketing Part Number	Sample Ordering Part Number
1	CY62177DV30LL-55BAXI	CY62177DV30LL-55XIKG
2	CY62177DV30LL-55BAXIT	CY62177DV30LL-55XIKG
3	CY62177EV18LL-70BAXI	Available to order, subject to lead time
4	CY62177EV18LL-70BAXIT	Available to order, subject to lead time
5	CY62177EV30LL-55BAXI	CY62177EV30LL-55XIKG
6	CY62177EV30LL-55BAXIT	CY62177EV30LL-55XIKG
7	CY7C1051DV33-10BAXI	CY7C1051DV33-10BAXIKG
8	CY7C1051DV33-10BAXIT	CY7C1051DV33-10BAXIKG
9	CY7C1071DV33-12BAXI	CY7C1071DV33-12BAXIKG
10	CY7C1071DV33-12BAXIT	CY7C1071DV33-12BAXIKG
11	CY7C1079DV33-12BAXI	Available to order, subject to lead time
12	CY7C1079DV33-12BAXIT	Available to order, subject to lead time
13	CG7552AT	Available to order, subject to lead time
14	CG7552ATT	Available to order, subject to lead time
15	CG7807AA	Available to order, subject to lead time
16	CG7807AAT	Available to order, subject to lead time

